AMENDMENTS TO THE SPECIFICATION:

Page 1, please replace the title with the following amended title:

--SEMICONDUCTOR INTEGRATED CIRCUIT~~, METHOD OF MANUFACTURING SEMICONDUCTOR INTEGRATED CIRCUIT, CHARGE PUMP CIRCUIT, LAYOUT DESIGNING APPARATUS, AND LAYOUT DESIGNING PROGRAM~~ HAVING TRANSISTORS FORMED ON AN INSULATING SUBSTRATE--

Page 1, replace the paragraph, beginning on line 13, bridging pages 1 and 2, with the following amended paragraph:

--For display devices and sensors, a method has generally been used in which peripheral circuits for driving a group of transistors (active matrix) for controlling display elements or sensor elements are mounted around a display region or a sensing region or formed on the same substrate as that for the active matrix (see, for example, patent documents 1 and 2 shown below). To increase the display region or the sensing region, the peripheral circuit is placed in straight narrow regions around the display region or the sensing region. A small-width peripheral circuit layout is made in such narrow regions, thus making it possible to provide a narrow-frame display device or sensor having an increased display or sensing region. Signal lines and power supply lines from external are connected by a flexible printed circuit (FPC) or the like to the peripheral circuits from a frame portion of the device. Therefore the external connection terminals of the peripheral circuits are concentrated on one side

and the degree of freedom of layout is low. On the other hand, there is a need to increase the width of power supply lines in comparison with that of other signal lines for the purpose of limiting a voltage drop and power consumption when large currents flow through the power supply lines by concentration of currents flowing through the circuits in the device.--

Page 3, replace the paragraph, beginning on line 5, with the following amended paragraph:

--FIG. 33 shows an example of an ordinary possible layout in a case where the power supply lines A32 and B33 are connected from an upper side of a layout to external points 50 and the power supply line a34 is wired in the layout. As wiring for internal connection, the power supply line a34 is extended downward as viewed in the figure so as not to increase the layout width. Similarly, as wiring for connection to external points, the power supply lines A32 and B33 are extended upward as viewed in the figure. However, the layout width is necessarily increased by an amount corresponding to the power supply line width W since the lines A32 and B33 are extended so as not to overlap each other. The layout area is thereby increased to (Lg + 3W) × 2Wg.--

Page 19, replace the paragraph, beginning on line 19, bridging pages 19 and 20, with the following amended paragraph:

--FIG. 3 is a diagram showing a layout which represents a second embodiment of the present invention. In this embodiment, a function for connection to external terminals 50 concentrated on

one side is added to the layout shown in FIG. 1. To externally apply potentials to the power supply lines A32 and B33, the power supply lines are extended upward as viewed in the figure in wiring using the first metal layer, thereby enabling connection through external connection terminals 50. The power supply line a34 is extended downward as viewed in the figure as wiring for connection to another internal circuit. This layout is characterized by avoiding an increase in width of the circuit layout even though wiring extensions are made.--

Page 22, replace the paragraph, beginning on line 7, with the following amended paragraph:

--FIG. 8 is a diagram showing a fifth embodiment of the present invention, which is a display device or a sensor. The display device or the sensor is constituted by display elements or sensor elements placed in matrix form in a display region or a sensing region 102, active matrix transistors for respectively driving the display elements or the sensor elements, peripheral circuits 103, a multilayer printed circuit board [[014]] 104 through which external signals and power are input or output, and a connection terminal 100. The active matrix transistors and the peripheral circuits 103 are constituted by thin film transistors formed on an insulation substrate or glass substrate 101 different from a semiconductor substrate. In the arrangement shown in FIG. 8, the wiring switching circuit shown in FIG. 4, for example, is placed in a peripheral circuit region 105. This circuit is used

for the purpose of switching between power supply voltages, or the like. Referring to an enlarged diagram shown in FIG. 9, the layout of the circuit is the same as that shown in FIG. 5, and electrodes A32 and B33 are extended for connection to the external connection terminal 100, and the ~~electrodes~~ power supply lines a34 and b35 are extended for connection to internal circuits.--